MOSFETs Silicon P-Channel MOS (U-MOSVI)

TJ9A10M3

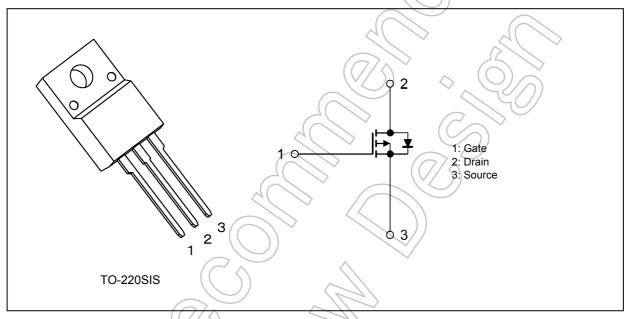
1. Applications

• Switching Voltage Regulators

2. Features

- (1) Low drain-source on-resistance: $R_{DS(ON)} = 120 \text{ m}\Omega$ (typ.) ($V_{GS} = -10 \text{ V}$)
- (2) Low leakage current: $I_{DSS} = -10 \ \mu A \ (max) \ (V_{DS} = -100 \ V)$
- (3) Enhancement mode: $V_{th} = -2.0$ to -4.0 V ($V_{DS} = -10$ V, $I_D = -1$ mA)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit	
Drain-source voltage			-100	V
Gate-source voltage		V _{GSS}	±20	
Drain current (DC)	(Note 1)	I _D	-9	Α
Drain current (pulsed)	(Note 1)	I _{DP}	-18	
Power dissipation $(T_c = 25^{\circ}C)$		PD	19	W
Single-pulse avalanche energy	(Note 2)	E _{AS}	25	mJ
Avalanche current		I _{AR}	-9	Α
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R _{th(ch-c)}	6.57	°C/W
Channel-to-ambient thermal resistance	R _{th(ch-a)}	62.5	1
lote 1: Ensure that the channel temperature does not exceed 150°C. lote 2: V _{DD} = -25 V, T _{ch} = 25°C (initial), L = 500 μ H, R _G = 25 Ω , I _{AR} = -9 A			
lote: This transistor is sensitive to electrostatic discharge and should be hand	led with care.		
		$\tilde{\mathcal{D}}$	
	$\mathcal{O}^{\mathcal{O}}$		
	15)		

6. Electrical Characteristics

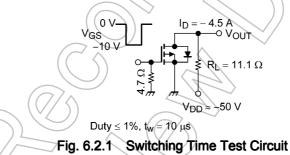
6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V	_	_	±0.1	μA
Drain cut-off current	I _{DSS}	V _{DS} = -100 V, V _{GS} = 0 V	K	_	-10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = -10 mA, V _{GS} = 0 V	-100	-	_	V
Drain-source breakdown voltage (Note 3)	V _{(BR)DSX}	I _D = -10 mA, V _{GS} = 20 V	-75)2		
Gate threshold voltage	V _{th}	V _{DS} = -10 V, I _D = -1 mA	-2.0	/_	-4.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = -10 V, I _D = -4.5 A	$\left(\right)$	120	170	mΩ
Forward transfer admittance	Y _{fs}	V _{DS} = -10 V, I _D = -4.5 A	_12	24	_	S

Note 3: If a reverse bias is applied between gate and source, this device enters V_{(BR)DSX} mode. Note that the drainsource breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz		2900) —	pF
Reverse transfer capacitance	C _{rss}		\sim	120	_	
Output capacitance	C _{oss}			[∼] 150	_	
Switching time (rise time)	tr	See Figure 6.2.1.	~_)	12	_	ns
Switching time (turn-on time)	t _{on}		\sim –	27	—	
Switching time (fall time)	t _f		ワー	32	—	
Switching time (turn-off time)	t _{off}		_	195		



6.3. Gate Charge Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

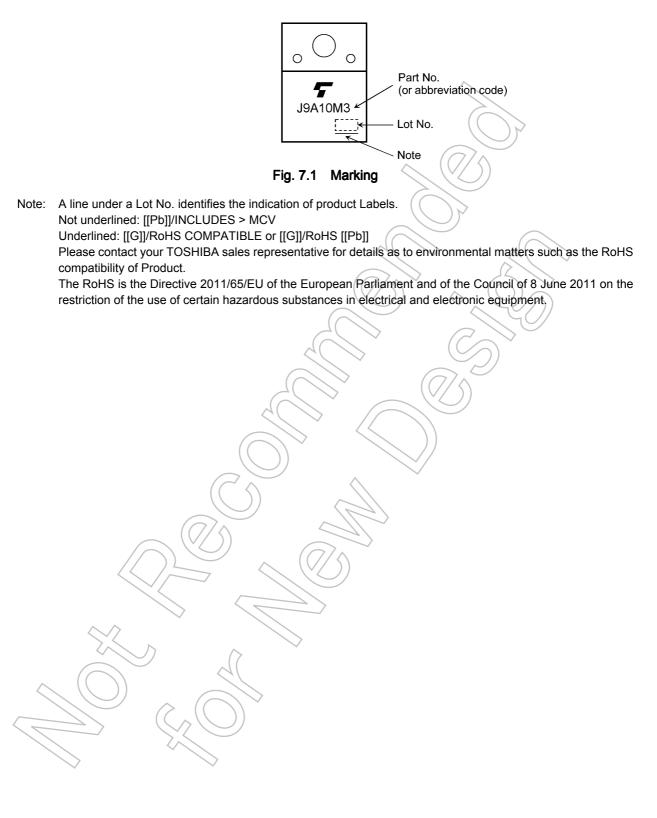
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx$ -80 V, V_{GS} = -10 V, I_D = -9 A	—	47	—	nC
Gate-source charge 1	Q _{gs1}			7.2	_	
Gate-drain charge	Q _{gd}		_	14	_	

6.4. Source-Drain Characteristics ($T_a = 25^{\circ}C$ unless otherwise specified)

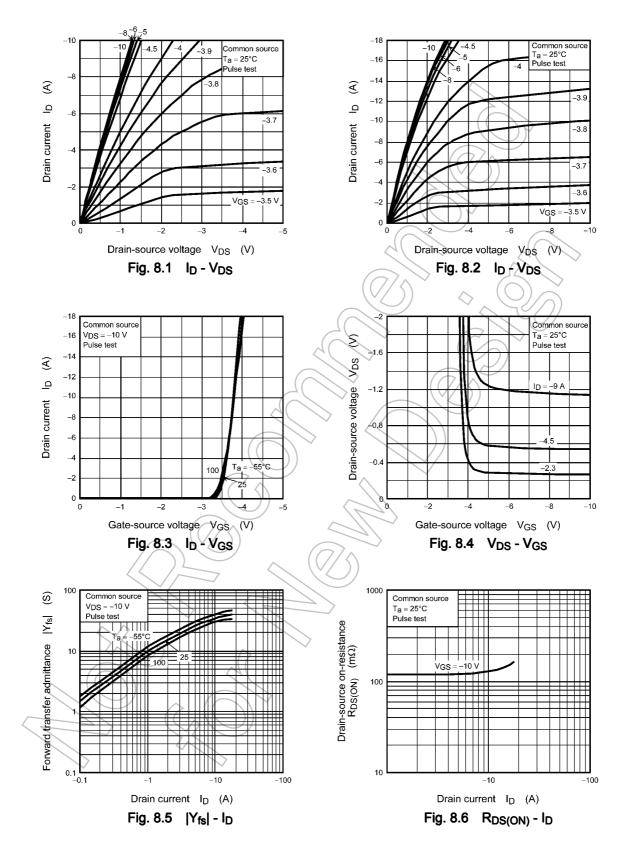
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 4)	I _{DR}	—	_	_	-9	A
Reverse drain current (pulsed)	(Note 4)	I _{DRP}		_	_	-18	
Diode forward voltage		V _{DSF}	I_{DR} = -9 A, V_{GS} = 0 V	-	—	1.4	V
Reverse recovery time			I _{DR} = -9 A, V _{GS} = 0 V		66	_	ns
Reverse recovery charge		Q _{rr}	dl _{DR} /dt = 50 A/µs	_	87	—	nC

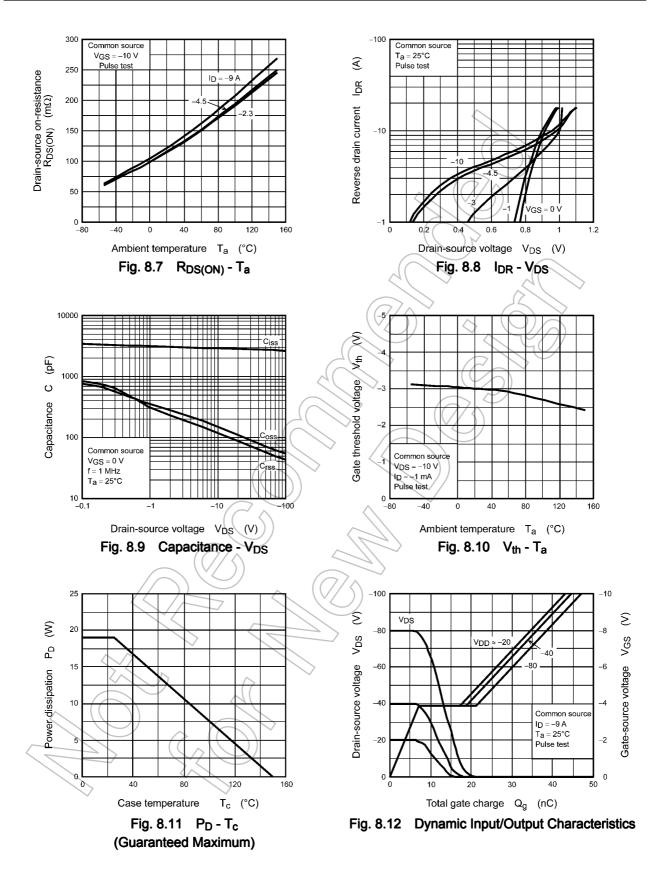
Note 4: Ensure that the channel temperature does not exceed 150°C.

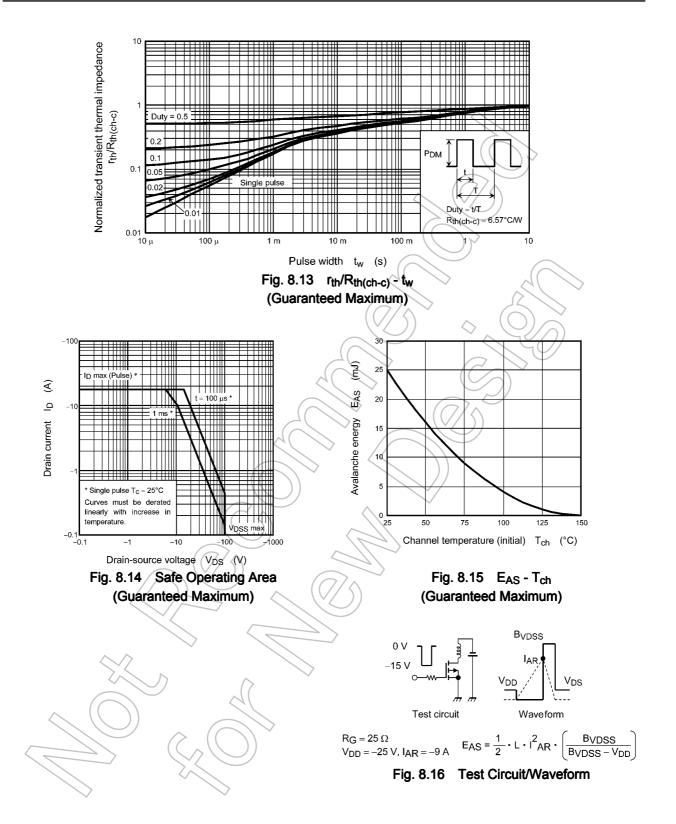
7. Marking (Note)



8. Characteristics Curves (Note)





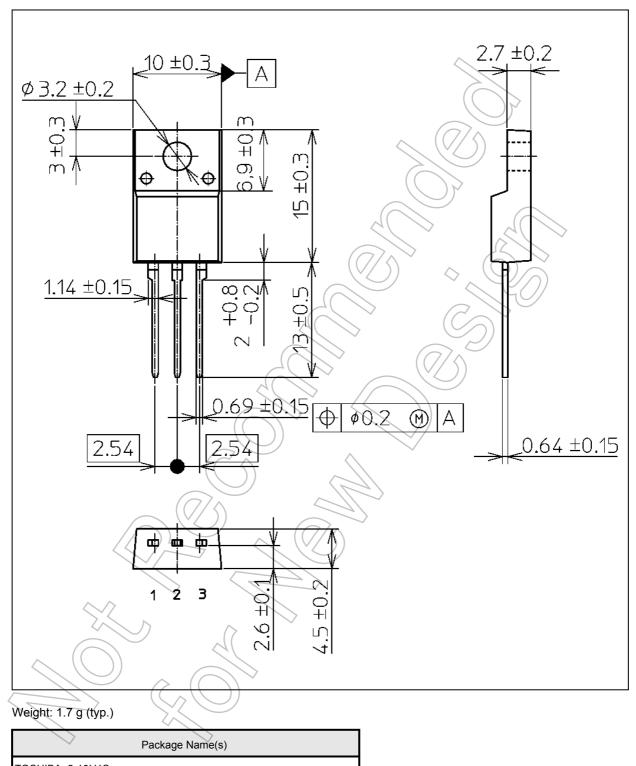


Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

TJ9A10M3

Unit: mm



TOSHIBA: 2-10U1S

Nickname: TO-220SIS

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